TOSHIBA Field Effect Transistor with Built-in Schottky Barrier Diode Silicon N-Channel MOS Type (U-MOS V-H)

# TPC8A03-H

High Efficiency DC-DC Converter Applications Notebook PC Applications Portable Equipment Applications

- Built-in schottky barrier diode
   Low forward voltage: V<sub>DSF</sub> = -0.6 V (max)
- · High-speed switching
- Small gate charge: Q<sub>SW</sub> = 8.4 nC (typ.)
- Low drain-source ON-resistance:  $R_{DS (ON)} = 4.1 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance: |Yfs| = 54 S (typ.)
- Low leakage current: I<sub>DSS</sub> = 100 μA (max) (V<sub>DS</sub> = 30 V)
- Enhancement mode:  $V_{th}$  = 1.3 to 2.3 V ( $V_{DS}$  = 10 V,  $I_D$  = 1 mA).

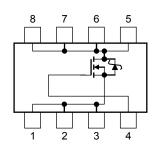
# Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	30	Y	
Drain-gate voltage (R <sub>GS</sub> = 20 kΩ)		V <sub>DGR</sub>	30	$\langle \vee$	
Gate-source voltage		V <sub>GS</sub> S	±20	V	
Drain current	DC (Note 1)	<b>P</b>	17	` A	
Drain current	Pulsed (Note 1)	((I <sub>DP</sub> ))	68	\\ ^	
Drain power dissipati	on (t = 10 s) (Note 2a)	PD	1.9	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	PD	(1.0)	W	
Single-pulse avalanche energy (Note 3)		EAS	188	mJ	
Avalanche current		I <sub>AR</sub>	17	Α	
Repetitive avalanche energy (Tc = 25°C) (Note 4)		EAR	0.108	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55 to 150	°C	

Note: For Notes 1 to 4, refer to the next page.

Weight: 0.085g (typ.)

#### **Circuit Configuration**



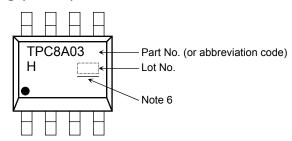
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.)

This transistor is an electrostatic-sensitive device. Handle with care.

#### **Thermal Characteristics**

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2a)	R <sub>th (ch-a)</sub>	65.8	°C/W
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2b)	R <sub>th (ch-a)</sub>	125	°C/W

#### Marking (Note 5)



Note 1: Ensure that the channel temperature does not exceed 150 C.

Note 2: (a) Device mounted on a glass-epoxy board (b) Device mounted on a glass-epoxy board (b)



Note 3:  $V_{DD} = 24 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial), L = 0.5 mH,  $R_G = 25 \Omega$ ,  $L_{R} = 17 \text{ A}$ 

Note 4: Repetitive rating: pulse width limited by maximum channel temperature

Note 5:

\* Weekly code: (Three digits)

Week of manufacture
(01 for first week of year, continuing up to 52 or 53)

Year of manufacture

(The last digit of the calendar year)

Note 6: A line under a Lot No. identifies the indication of product Labels.

Not underlined: [[Pb]]/INCLUDES > MCV

Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

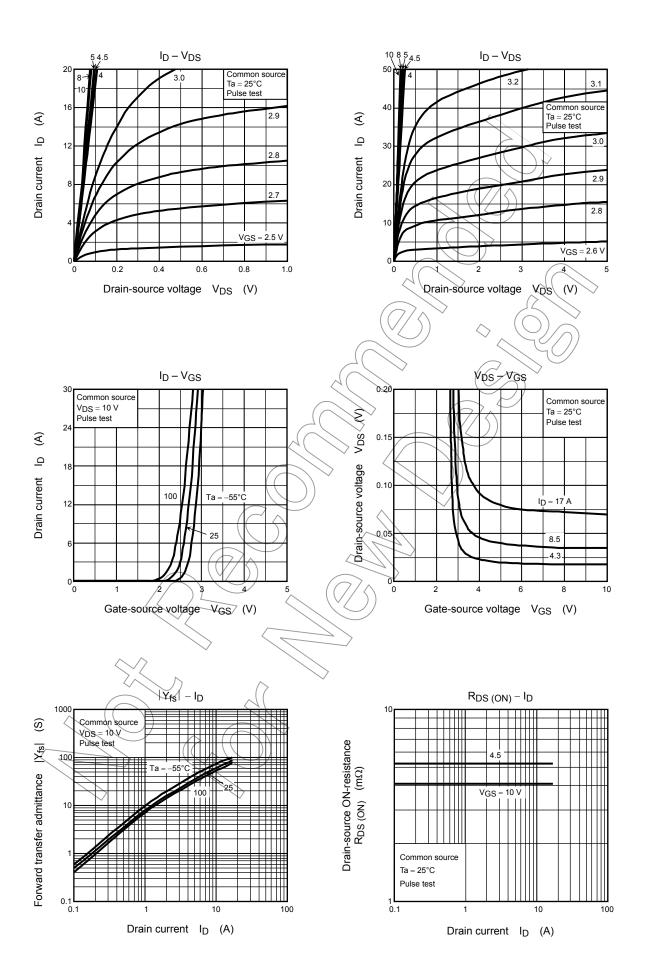
Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

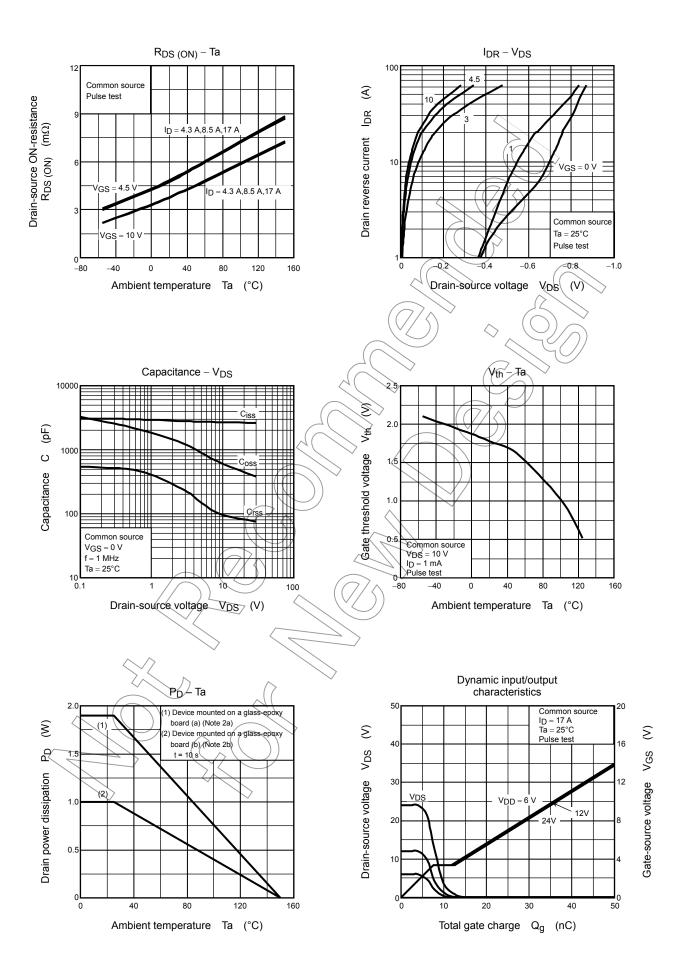
### **Electrical Characteristics (Ta = 25°C)**

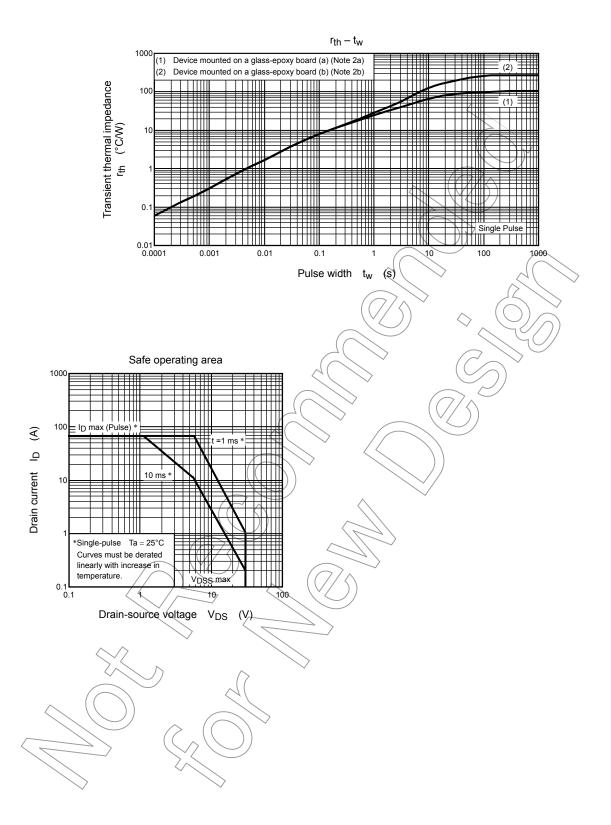
Cha	aracteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage curr	ent	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±100	nA
Drain cut-off curre	nt	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V	_	_	100	μА
Drain-source breakdown voltage		V <sub>(BR) DSS</sub>	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	30	_	_	٧
		V <sub>(BR) DSX</sub>	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	15	_	_	
Gate threshold vo	Itage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.3	) / _	2.3	V
Drain-source ON-resistance		-	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 8.5 A	> <u>~</u>	5.1	7.0	- mΩ
		R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 8.5 A	$\bigcirc))$	4.1	5.6	
Forward transfer a	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 8.5 A	27	54	_	S
Input capacitance		C <sub>iss</sub>		_	2640	3430	
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	100	150	pF
Output capacitance		C <sub>oss</sub>			610	$\nearrow$	
Gate resistance		rg	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 5 MHz	-6	1.0	7.5	Ω
Switching time	Rise time	t <sub>r</sub>	10 V T ID = 8.5 A	7	3.6	) _	
	Turn-on time	t <sub>on</sub>	VGS OV GS OVOUT	$\overline{\mathcal{I}}$	11.0	_	ne
	Fall time	t <sub>f</sub>	4. w w o K		7.2	_	ns
	Turn-off time	t <sub>off</sub>	Duty ≤ 1%, t <sub>W</sub> = 10 μs	<i>_</i>	42	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 17 \text{ A}$	_	36	_	
			$V_{DD} \approx 24 \text{ V}, V_{GS} = 5 \text{ V}, V_{D} \neq 17 \text{ A}$		19		
Gate-source charg	ge 1 (	Q <sub>gs1</sub>			7.6		nC
Gate-drain ("Miller") charge		Q <sub>gd</sub>	$V_{DD} \approx 24 \text{ V, V}_{GS} = 10 \text{ V, I}_{D} = 17 \text{ A}$	_	5.0	_	
Gate switch charge		Q <sub>SW</sub>		_	8.4	_	

## Source-Drain Ratings and Characteristics (Ta = 25°C)

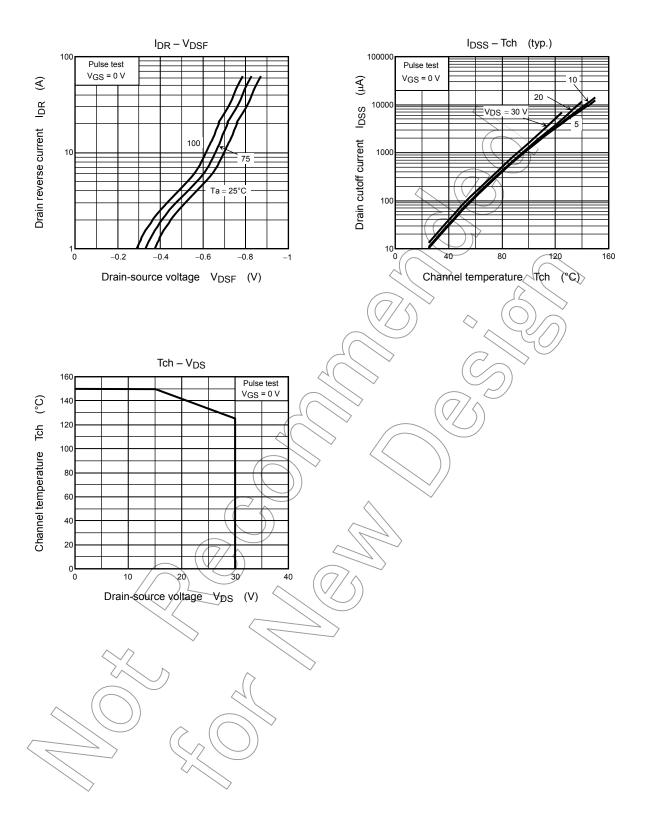
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current Pulse (Note 1)	I <sub>DRP</sub>	> -	_	_	68	Α
Forward voltage (diode)		I <sub>DR</sub> = 1 A, V <sub>GS</sub> = 0 V		- 0.4	- 0.6	V
of ward voltage (diode)	VDSF	$I_{DR} = 17 \text{ A}, V_{GS} = 0 \text{ V}$			- 1.2	V







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